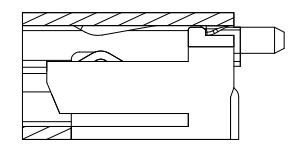
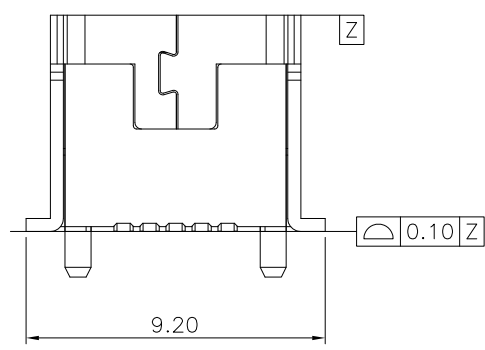


P.C.B LAYOUT MOUNTING PATTERN



MATERIAL SPECIFICATION:

- 1. HOUSING:LCP
- 2. CONTACT:PHOSPHOR BRONZE
- 3. SHELL:BRASS

FINISH:

- 1.Contact:Plated Gold in Mating Area;
Tin Plated on Solder Balls;
Nickel under plated overall.
- 2.Shell:Nickel under Plated surface layer

ELECTRICAL PERFORMANCE

- 1. RATED VOLTAGE(MAX.):AC 30V
- 2. RATED CURRENT(MAX.):AC 1.0A CONTACT RESISTANCE
- 3. CONTACT RESISTANCE:50mΩ MAX
- 4. DIELECTRIC WITHSTANDING VOLTAGE:100V AC MIN
- 5. INSULATION RESISTANCE:100MΩ MIN
- 6. INSERTION FORCE:3.57Kgf MAX
- 7. EXTRACTION FORCE:0.714Kgf MIN INITIAL
- 8. SERVICE LIFE:5,000 TIMES Above

ITEM NO.	DESCRIPTION	DRAWN	DATE
5	更新圖面及SPEC	Jack	060713
4	更新材質及SPEC	Jack	060313
3	更新圖面	Jack	042513
2	新增接腳編號	Jack	040213
1	新增尺寸	Jack	032913

東莞市高迪電子有限公司
DONG GUAN GAO DI ELECTRONICS CO., LTD

TOLERANCE UNLESS OTHERWISE STATED :
 Up to 5 ±0.2
 Above 5 ~ 15 ±0.3
 Above 15 ~ 30 ±0.4
 Above 30 ~ 50 ±0.5
 Angle ±0.3

3RD. ANGEL'S

UNITS MM

DRAWN BY:	DATE	MAT'L	TITLE	CONNECTOR
Jack Lu	06/07/13	FINISH	MODLE	MINI USB 5PF 180 度 SMT
CHECKED BY:	DATE	SCALE	DWG NO.	MUSB-5B-VSE-S165
Jacky Chen	06/07/13	SHEET NO.	PART NO.	MUSB-5B-VSE-S165
APPROVED BY:	DATE			SIZE
Tony Kao	06/07/13			A4
				VER
				R5